Intel - 5AGXBB7D4F35C4N Datasheet





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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	23780
Number of Logic Elements/Cells	504000
Total RAM Bits	27695104
Number of I/O	544
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxbb7d4f35c4n

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Caution: Conditions outside the range listed in the following table may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 1-1: Absolute Maximum Ratings for Arria V Devices

Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Core voltage power supply	-0.50	1.43	V
V _{CCP}	Periphery circuitry, PCIe [®] hardIP block, and transceiver physical coding sublayer (PCS) power supply	-0.50	1.43	V
V _{CCPGM}	Configuration pins power supply	-0.50	3.90	V
V _{CC_AUX}	Auxiliary supply	-0.50	3.25	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	-0.50	3.90	V
V _{CCPD}	I/O pre-driver power supply	-0.50	3.90	V
V _{CCIO}	I/O power supply	-0.50	3.90	V
V _{CCD_FPLL}	Phase-locked loop (PLL) digital power supply	-0.50	1.80	V
V _{CCA_FPLL}	PLL analog power supply	-0.50	3.25	V
V _{CCA_GXB}	Transceiver high voltage power	-0.50	3.25	V
V _{CCH_GXB}	Transmitter output buffer power	-0.50	1.80	V
V _{CCR_GXB}	Receiver power	-0.50	1.50	V
V _{CCT_GXB}	Transmitter power	-0.50	1.50	V
V _{CCL_GXB}	Transceiver clock network power	-0.50	1.50	V
VI	DC input voltage	-0.50	3.80	V
V _{CC_HPS}	HPS core voltage and periphery circuitry power supply	-0.50	1.43	V
V _{CCPD_HPS}	HPS I/O pre-driver power supply	-0.50	3.90	V
V _{CCIO_HPS}	HPS I/O power supply	-0.50	3.90	V
V _{CCRSTCLK_HPS}	HPS reset and clock input pins power supply	-0.50	3.90	V



Symbol	Description	Condition	Minimum ⁽¹⁾	Typical	Maximum ⁽¹⁾	Unit
		3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
V	1/O buffers newer supply	1.8 V	1.71	1.8	1.89	V
V CCIO	1/O bullets power supply	1.5 V	1.425	1.5	1.575	V
		1.35 V	1.283	1.35	1.418	V
		1.25 V	1.19	1.25	1.31	V
		1.2 V	1.14	1.2	1.26	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply	_	1.425	1.5	1.575	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply	_	2.375	2.5	2.625	V
V _I	DC input voltage	_	-0.5	_	3.6	V
V _O	Output voltage	_	0	_	V _{CCIO}	V
T	Operating junction temperature	Commercial	0	_	85	°C
тj	Operating junction temperature	Industrial	-40	_	100	°C
+ (4)	Power supply ramp time	Standard POR	200 µs	_	100 ms	_
t _{RAMP} ⁽⁴⁾	Power supply ramp time	Fast POR	200 µs	_	4 ms	_



⁽¹⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽⁴⁾ This is also applicable to HPS power supply. For HPS power supply, refer to t_{RAMP} specifications for standard POR when HPS_PORSEL = 0 and t_{RAMP} specifications for fast POR when HPS_PORSEL = 1.

Symbol	Description	Minimum ⁽⁵⁾	Typical	Maximum ⁽⁵⁾	Unit
V _{CCL_GXBL}	GX and SX speed grades—clock network power (left side)	1 08/1 12	1 1/1 15(6)	1 14/1 18	V
V _{CCL_GXBR}	GX and SX speed grades—clock network power (right side)	1.00/ 1.12	1.1/1.13	1.14/1.10	v
V _{CCL_GXBL}	GT and ST speed grades—clock network power (left side)	117	1 20	1 22	V
V _{CCL_GXBR}	GT and ST speed grades—clock network power (right side)	1.17	1.20	1.23	v

Related Information

Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines

Provides more information about the power supply connection for different data rates.

HPS Power Supply Operating Conditions

Table 1-5: HPS Power Supply Operating Conditions for Arria V SX and ST Devices

This table lists the steady-state voltage and current values expected from Arria V system-on-a-chip (SoC) devices with ARM®-based hard processor system (HPS). Power supply ramps must all be strictly monotonic, without plateaus. Refer to Recommended Operating Conditions for Arria V Devices table for the steady-state voltage values expected from the FPGA portion of the Arria V SoC devices.

Symbol	Description	Condition	Minimum ⁽⁷⁾	Typical	Maximum ⁽⁷⁾	Unit
	HPS core	-C4, -I5, -C5, -C6	1.07	1.1	1.13	V
V _{CC_HPS}	voltage and periphery circuitry power supply	-I3	1.12	1.15	1.18	V

⁽⁵⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.



⁽⁷⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Symbol	Description	V _{CCIO} (V)	Value	Unit
dR/dT		3.0	0.189	
		2.5	0.208	
	OCT variation with temperature without recalibration	1.8	0.266	
		1.5	0.273	%/°C
		1.35	0.200	
		1.25	0.200	
		1.2	0.317	

Pin Capacitance

Table 1-11: Pin Capacitance for Arria V Devices

Symbol	Description	Maximum	Unit
C _{IOTB}	Input capacitance on top/bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on left/right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output/feedback pins	6	pF
C _{IOVREF}	Input capacitance on V _{REF} pins	48	pF

Hot Socketing

Table 1-12: Hot Socketing Specifications for Arria V Devices

Symbol	Description	Maximum	Unit
I _{IOPIN (DC)}	DC current per I/O pin	300	μΑ
I _{IOPIN (AC)}	AC current per I/O pin	8(10)	mA
I _{XCVR-TX (DC)}	DC current per transceiver transmitter (TX) pin	100	mA

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For example, when V_{OD} = 800 mV, the corresponding V_{OD} value setting is 40. The following conditions show that the 1st post tap pre-emphasis setting = 2 is valid:

- $|B| + |C| \le 60 \Rightarrow 40 + 2 = 42$ ٠
- $|B| |C| > 5 \rightarrow 40 2 = 38$
- $(V_{MAX}/V_{MIN} 1)\% < 600\% \Rightarrow (42/38 1)\% = 10.52\%$

To predict the pre-emphasis level for your specific data rate and pattern, run simulations using the Arria V HSSI HSPICE models.

Table 1-33: Transmitter Pre-Emphasis Levels for Arria V Devices

Quartus Prime 1st								
Post Tap Pre- Emphasis Setting	10 (200 mV)	20 (400 mV)	30 (600 mV)	35 (700 mV)	40 (800 mV)	45 (900 mV)	50 (1000 mV)	Unit
0	0	0	0	0	0	0	0	dB
1	1.97	0.88	0.43	0.32	0.24	0.19	0.13	dB
2	3.58	1.67	0.95	0.76	0.61	0.5	0.41	dB
3	5.35	2.48	1.49	1.2	1	0.83	0.69	dB
4	7.27	3.31	2	1.63	1.36	1.14	0.96	dB
5	_	4.19	2.55	2.1	1.76	1.49	1.26	dB
6	_	5.08	3.11	2.56	2.17	1.83	1.56	dB
7	_	5.99	3.71	3.06	2.58	2.18	1.87	dB
8	_	6.92	4.22	3.47	2.93	2.48	2.11	dB
9	_	7.92	4.86	4	3.38	2.87	2.46	dB
10	_	9.04	5.46	4.51	3.79	3.23	2.77	dB
11	_	10.2	6.09	5.01	4.23	3.61	_	dB
12	_	11.56	6.74	5.51	4.68	3.97	_	dB
13	_	12.9	7.44	6.1	5.12	4.36	_	dB
14	_	14.44	8.12	6.64	5.57	4.76	_	dB
15	_	_	8.87	7.21	6.06	5.14	_	dB

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Memory Output Clock Jitter Specifications

Table 1-45: Memory Output Clock Jitter Specifications for Arria V Devices

The memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2/DDR3 SDRAM standard. The memory output clock jitter is applicable when an input jitter of 30 ps (p-p) is applied with bit error rate (BER) 10^{-12} , equivalent to 14 sigma. Altera recommends using the UniPHY intellectual property (IP) with PHYCLK connections for better jitter performance.

Parameter	Clock Notwork	Symbol	-I3,	-C4	–15,	-C5	_(6	Unit
		Symbol	Min	Max	Min	Max	Min	Max	onit
Clock period jitter	PHYCLK	t _{JIT(per)}	-41	41	-50	50	-55	55	ps
Cycle-to-cycle period jitter	PHYCLK	t _{JIT(cc)}	6	3	9	0	9	94	ps

OCT Calibration Block Specifications

Table 1-46: OCT Calibration Block Specifications for Arria V Devices

Symbol	Description	Min	Тур	Max	Unit
OCTUSRCLK	Clock required by OCT calibration blocks	_		20	MHz
T _{OCTCAL}	Number of octus RCLK clock cycles required for $R_{\rm S}$ OCT/R_T OCT calibration		1000		Cycles
T _{OCTSHIFT}	Number of OCTUSRCLK clock cycles required for OCT code to shift out		32	_	Cycles
T _{RS_RT}	Time required between the dyn_term_ctrl and oe signal transitions in a bidirectional I/O buffer to dynamically switch between R_S OCT and R_T OCT	_	2.5		ns



Figure 1-10: SPI Slave Timing Diagram



Related Information

SPI Controller, Arria V Hard Processor System Technical Reference Manual

Provides more information about rx_sample_delay.

SD/MMC Timing Characteristics

Table 1-54: Secure Digital (SD)/MultiMediaCard (MMC) Timing Requirements for Arria V Devices

After power up or cold reset, the Boot ROM uses drvsel = 3 and smplsel = 0 to execute the code. At the same time, the SD/MMC controller enters the Identification Phase followed by the Data Phase. During this time, the value of interface output clock SDMMC_CLK_OUT changes from a maximum of 400 kHz (Identification Phase) up to a maximum of 12.5 MHz (Data Phase), depending on the internal reference clock SDMMC_CLK and the CSEL setting. The value of SDMMC_CLK is based on the external oscillator frequency and has a maximum value of 50 MHz.



Figure 1-15: MDIO Timing Diagram



I²C Timing Characteristics

Table 1-59: I²C Timing Requirements for Arria V Devices

Symbol	Description	Standar	d Mode	Fast l	Mode	Unit
Symbol	Description	Min	Max	Min	Max	Ont
T _{clk}	Serial clock (SCL) clock period	10	—	2.5		μs
T _{clkhigh}	SCL high time	4.7	—	0.6		μs
T _{clklow}	SCL low time	4	—	1.3		μs
T _s	Setup time for serial data line (SDA) data to SCL	0.25	—	0.1		μs
T _h	Hold time for SCL to SDA data	0	3.45	0	0.9	μs
T _d	SCL to SDA output data delay	—	0.2		0.2	μs
T _{su_start}	Setup time for a repeated start condition	4.7	_	0.6		μs
T _{hd_start}	Hold time for a repeated start condition	4	_	0.6		μs
T _{su_stop}	Setup time for a stop condition	4	_	0.6	_	μs



Figure 1-16: I²C Timing Diagram



NAND Timing Characteristics

Table 1-60: NAND ONFI 1.0 Timing Requirements for Arria V Devices

The NAND controller supports Open NAND FLASH Interface (ONFI) 1.0 Mode 5 timing as well as legacy NAND devices. This table lists the requirements for ONFI 1.0 mode 5 timing. The HPS NAND controller can meet this timing by programming the c4 output of the main HPS PLL and timing registers provided in the NAND controller.

Symbol	Description	Min	Max	Unit
T _{wp} ⁽⁸⁹⁾	Write enable pulse width	10	—	ns
T _{wh} ⁽⁸⁹⁾	Write enable hold time	7		ns
T _{rp} ⁽⁸⁹⁾	Read enable pulse width	10		ns
T _{reh} ⁽⁸⁹⁾	Read enable hold time	7		ns
T _{clesu} ⁽⁸⁹⁾	Command latch enable to write enable setup time	10		ns
T _{cleh} ⁽⁸⁹⁾	Command latch enable to write enable hold time	5		ns
T _{cesu} ⁽⁸⁹⁾	Chip enable to write enable setup time	15		ns
T _{ceh} ⁽⁸⁹⁾	Chip enable to write enable hold time	5		ns
T _{alesu} ⁽⁸⁹⁾	Address latch enable to write enable setup time	10		ns
T _{aleh} ⁽⁸⁹⁾	Address latch enable to write enable hold time	5		ns
T _{dsu} ⁽⁸⁹⁾	Data to write enable setup time	10		ns

⁽⁸⁹⁾ Timing of the NAND interface is controlled through the NAND configuration registers.



HPS JTAG Timing Specifications

Symbol	Description	Min	Max	Unit
t _{JCP}	TCK clock period	30	_	ns
t _{JCH}	TCK clock high time	14		ns
t _{JCL}	TCK clock low time	14		ns
t _{JPSU (TDI)}	TDI JTAG port setup time	2		ns
t _{JPSU (TMS)}	TMS JTAG port setup time	3		ns
t _{JPH}	JTAG port hold time	5		ns
t _{JPCO}	JTAG port clock to output		12 ⁽⁹⁰⁾	ns
t _{JPZX}	JTAG port high impedance to valid output		14 ⁽⁹⁰⁾	ns
t _{JPXZ}	JTAG port valid output to high impedance		14 ⁽⁹⁰⁾	ns

Table 1-62: HPS JTAG Timing Parameters and Values for Arria V Devices

Configuration Specifications

This section provides configuration specifications and timing for Arria V devices.

POR Specifications

Table 1-63: Fast and Standard POR Delay Specification for Arria V Devices

POR Delay	Minimum	Maximum	Unit
Fast	4	12 ⁽⁹¹⁾	ms

⁽⁹⁰⁾ A 1-ns adder is required for each V_{CCIO_HPS} voltage step down from 3.0 V. For example, t_{JPCO} = 13 ns if V_{CCIO_HPS} of the TDO I/O bank = 2.5 V, or 14 ns if it equals 1.8 V.

⁽⁹¹⁾ The maximum pulse width of the fast POR delay is 12 ms, providing enough time for the PCIe hard IP to initialize after the POR trip.



1-82 PS Configuration Timing

Symbol	Parameter	Minimum	Maximum	Unit
$t_{CF2CK}^{(105)}$	nCONFIG high to first rising edge on DCLK	1506	—	μs
t _{ST2CK} ⁽¹⁰⁵⁾	nSTATUS high to first rising edge of DCLK	2		μs
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5		ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0	_	ns
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$		S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$		S
t _{CLK}	DCLK period	1/f _{MAX}	—	S
f_{MAX}	DCLK frequency	_	125	MHz
t _{CD2UM}	CONF_DONE high to user mode ⁽¹⁰⁶⁾	175	437	μs
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	$4 \times \text{maximum DCLK period}$	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (T_{init} × CLKUSR period)	_	_
T _{init}	Number of clock cycles required for device initialization	8,576		Cycles

Related Information

PS Configuration Timing

Provides the PS configuration timing waveform.



 $^{^{(105)}}$ If <code>nstatus</code> is monitored, follow the t_{ST2CK} specification. If <code>nstatus</code> is not monitored, follow the t_{CF2CK} specification.

⁽¹⁰⁶⁾ The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

Symbol	Description	Minimum ⁽¹¹⁸⁾	Typical	Maximum ⁽¹¹⁸⁾	Unit
		0.82	0.85	0.88	
V _{CCR_GXBL} ⁽¹²¹⁾	Receiver analog power supply (left side)	0.97	1.0	1.03	V
		1.03	1.05	1.07	
		0.82	0.85	0.88	
V _{CCR_GXBR} ⁽¹²¹⁾	Receiver analog power supply (right side)	0.97	1.0	1.03	V
		1.03	1.05	1.07	
	Transmitter analog power supply (left side)	0.82	0.85	0.88	
V _{CCT_GXBL} ⁽¹²¹⁾		0.97	1.0	1.03	V
		1.03	1.05	1.07	
		0.82	0.85	0.88	
V _{CCT_GXBR} ⁽¹²¹⁾	Transmitter analog power supply (right side)	0.97	1.0	1.03	V
		1.03	1.05	1.07	
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	1.425	1.5	1.575	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	1.425	1.5	1.575	V



⁽¹¹⁸⁾ This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽¹²¹⁾ This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rate up to 6.5 Gbps, you can connect this supply to 0.85 V.

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Sumbol/Description	Conditions	Transceiver Speed Grade 2			Transce	eiver Speed (Unit	
Symbol/Description	Conditions -	Min	Тур	Мах	Min	Тур	Мах	
	100 Hz	—	_	-70	—	—	-70	dBc/Hz
	1 kHz	—	—	-90		—	-90	dBc/Hz
Transmitter REFCLK Phase Noise (622 MHz) ⁽¹⁴¹⁾	10 kHz	—	—	-100	_	—	-100	dBc/Hz
	100 kHz	—	—	-110	_	—	-110	dBc/Hz
	≥1 MHz	—	—	-120		—	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁴²⁾	10 kHz to 1.5 MHz (PCIe)	_	_	3	_	_	3	ps (rms)
R _{REF}	—	—	1800 ±1%	_		1800 ±1%		Ω

Related Information

Arria V Device Overview

For more information about device ordering codes.

Transceiver Clocks

Table 2-23: Transceiver Clocks Specifications for Arria V GZ Devices

Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the Arria V Device Overview.

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 $^{^{(141)}}$ To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20 *log(f/622).

⁽¹⁴²⁾ To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz \times 100/f.

Sumbol/Description	Conditions	Trans	ceiver Spee	d Grade 2	Transo	Unit		
Symbol/Description	Conditions	Min	Тур	Max	Min	Тур	Max	
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_ clk) frequency	—	100		125	100	_	125	MHz

Related Information

Arria V Device Overview

For more information about device ordering codes.

Receiver

Table 2-24: Receiver Specifications for Arria V GZ Devices

Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Arria V Device Overview*.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transc	Unit		
Symbol Description	Conditions	Min	Тур	Max	Min	Тур	Мах	Onic
Supported I/O Standards	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS							
Data rate (Standard PCS) (143), (144)	—	600		9900	600	_	8800	Mbps
Data rate (10G PCS) (143), (144)	_	600		12500	600	_	10312.5	Mbps
Absolute $\mathrm{V}_{\mathrm{MAX}}$ for a receiver pin $^{(145)}$	—			1.2			1.2	V
Absolute V_{MIN} for a receiver pin	_	-0.4	_		-0.4	_	_	V

⁽¹⁴³⁾ The line data rate may be limited by PCS-FPGA interface speed grade.

⁽¹⁴⁴⁾ To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.



⁽¹⁴⁵⁾ The device cannot tolerate prolonged operation at this absolute maximum.

Table 2-26: CMU PLL Specifications for Arria V GZ Devices

Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the Arria V Device Overview.

Symbol/Description	Conditions	Conditions Transceiver Speed Grade 2			Transc	Unit		
	Conditions	Min	Тур	Max	Min	Тур	Мах	Onit
Supported data range	_	600	_	12500	600	_	10312.5	Mbps
t _{pll_powerdown} ⁽¹⁵³⁾	—	1			1	_		μs
t _{pll_lock} ⁽¹⁵⁴⁾	_			10			10	μs

Related Information

Arria V Device Overview

For more information about device ordering codes.

ATX PLL

Table 2-27: ATX PLL Specifications for Arria V GZ Devices

Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the Arria V Device Overview.

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 $t_{pll_powerdown}$ is the PLL powerdown minimum pulse width. (153)

⁽¹⁵⁴⁾ $t_{\text{pll} \text{ lock}}$ is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.

Figure 2-2: AC Gain Curves for Arria V GZ Channels (full bandwidth)







Symbol	Conditions	C3, I3L			C4, I4			Unit
Symbol	Conditions	Min	Тур	Мах	Min	Тур	Max	Onic
	SERDES factor J = 3 to 10 (192), (193), (194), (195), (196), (197)	150	_	1250	150	—	1050	Mbps
True Differential I/O Standards - f _{HSDRDPA} (data rate)	SERDES factor $J \ge 4$ LVDS RX with DPA (193), (195), (196), (197)	150	_	1600	150		1250	Mbps
(data rate)	SERDES factor J = 2, uses DDR Registers	(198)	_	(199)	(198)		(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	_	(199)	(198)		(199)	Mbps
	SERDES factor $J = 3$ to 10	(198)	—	(200)	(198)	—	(200)	Mbps
f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)		(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps

 $^{(192)}$ The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design dependent and requires timing analysis.

⁽¹⁹³⁾ Arria V GZ RX LVDS will need DPA. For Arria V GZ TX LVDS, the receiver side component must have DPA.

⁽¹⁹⁴⁾ Arria V GZ LVDS serialization and de-serialization factor needs to be x4 and above.

⁽¹⁹⁵⁾ Requires package skew compensation with PCB trace length.

⁽¹⁹⁶⁾ Do not mix single-ended I/O buffer within LVDS I/O bank.

⁽¹⁹⁷⁾ Chip-to-chip communication only with a maximum load of 5 pF.

⁽¹⁹⁸⁾ The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.

⁽¹⁹⁹⁾ The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.

⁽²⁰⁰⁾ You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.



Number of DQS Delay Buffers	C3, I3L	C4, I4	Unit
4	120	128	ps

Memory Output Clock Jitter Specifications

Table 2-50: Memory Output Clock Jitter Specification for Arria V GZ Devices

The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.

The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.

The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

Clock Network	Parameter	Symbol	C3, I3L		C4, I4		Unit
			Min	Мах	Min	Мах	Onit
Regional	Clock period jitter	t _{JIT(per)}	-55	55	-55	55	ps
	Cycle-to-cycle period jitter	t _{JIT(cc)}	-110	110	-110	110	ps
	Duty cycle jitter	t _{JIT(duty)}	-82.5	82.5	-82.5	82.5	ps
Global	Clock period jitter	t _{JIT(per)}	-82.5	82.5	-82.5	82.5	ps
	Cycle-to-cycle period jitter	t _{JIT(cc)}	-165	165	-165	165	ps
	Duty cycle jitter	t _{JIT(duty)}	-90	90	-90	90	ps
PHY Clock	Clock period jitter	t _{JIT(per)}	-30	30	-35	35	ps
	Cycle-to-cycle period jitter	t _{JIT(cc)}	-60	60	-70	70	ps
	Duty cycle jitter	t _{JIT(duty)}	-45	45	-56	56	ps



Table 2-55: DCLK-to-DATA[] Ratio for Arria V GZ Devices

Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA[] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Arria V GZ devices use the additional clock cycles to decrypt and decompress the configuration data.

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio	
	Disabled	Disabled	1	
FDD V8	Disabled	Enabled	1	
111 ×0	Enabled	Disabled	2	
	Enabled	Enabled	2	
	Disabled	Disabled	1	
FDD v16	Disabled	Enabled	2	
111 ×10	Enabled	Disabled	4	
	Enabled	Enabled	4	
	Disabled	Disabled	1	
FDD × 32	Disabled	Enabled	4	
111 ~52	Enabled	Disabled	8	
	Enabled	Enabled	8	





Term				Definition				
R _L	Receiver differential input discrete resistor (external to the Arria V GZ device).							
SW (sampling window)	Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown:							
		Bit Time						
		0.5 x TCCS	RSKM	Sampling Window (SW)	RSKM	0.5 x TCCS		
Single-ended voltage referenced I/O standard	The JEDEC standard for SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state. The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing: Single-Ended Voltage Referenced I/O Standard							
		V _{0H}		V REF	Viн(DC Vil(DC)	V <u>ccio</u> VIH(AC) VIL(AC) VIL(AC)		

